

Reply to queries

Tender no. RailTel/Tender/OT/CO/P/2022-23/LIMS/003 dated:13.06.2022

Technical specifications, Chapter-3:-

SN	Clause No. & Chapter No.	Page No.	Sub Clause no./Point no.	Content of the clause requires clarification	Points of clarification required	Remarks	RailTel's Resonse
1	1.2	14	2. Memory	512 GB, DDR4-2933 (32x16 GB) , expandable to 1TB	Kindly change it to "512 GB, DDR4-2933 (16 x 32GB DIMM), expandable to 1.5TB without replacing the existing modules"	Suggesting higher expandability of memory without replacing the existing modules	See corrigendum-III
2	1.2	14	4. Hard Disk Controller	SAS RAID Controller (RAID 5/6) up to 12 Gbps with 2 GB Cache	Kindly change it to "RAID Controller (RAID 5/6) up to 12 Gbps with 8 GB Cache"	Better cache on the RAID controller will enable better management of internal drives	See corrigendum-III
3	1.2	14	6. Graphics	Integrated SVGA graphics interface	Kindly change it to "Integrated VGA graphics interface"	The servers have only VGA card/port available to connect to an external monitor. Since these servers will be deployed in Data centre, they will generally be remotely managed.	See corrigendum-III
4	1.2	14	7. Network Interface	(b)1x100 Gigabit (Mellanox Connect-X5 100 GbE with Mellanox SFP QSFP28)	Kindly change it to "2x100 Gigabit (Mellanox Connect-X5 100 GbE with Mellanox/ Compatible SFP QSFP28"	Please note that Mellanox transceivers have very high delivery times. Hence request if compatible Transceivers can be used which will have lesser delivery times.	As per RFP
5	1.2	15	8. PCI slots	8x PCIe Gen 3.0 (x16) I/O expansion slots (at least 4 Nos. PCIe x8 or above and at least 4 Nos. of PCIe x16 full length, Full Height)	Kindly change it to "Up to 6 x Gen3 slots, (4x16 slots or 2x16 + 4x8 slots)"	The server specifications match to that of a dense server having only 2U rack space. Also since the reqt of PCI slots is limited, hence requesting for the change.	See corrigendum-III
6	Addition al	15	-	-	2U Rack Mountable with sliding rails and accessories	This will ensure a minimum rack space being allocated for the server	As per RFP
7	Addition al	15	-	-	Security Features Like --- Cryptographically signed firmware Silicon Root of Trust; Secure Boot ; System Lockdown; System Erase	These features will help enhance the overall security of the server	As per RFP
8	Addition al	15	-	-	OS Support --- Citrix XenServer 7.6 Microsoft Windows Server 2019 with Hyper-V Oracle Linux 7.5 Red Hat Enterprise Linux 8.0 SuSE Linux Enterprise Server 15 Canonical Ubuntu LTS 18.04 VMWare ESXi 6.7 U2 VMWare ESXi 6.5 U3	These features are to ensure maximum supportability	As per RFP

9	1.1	14	5(a)	IP Packet Load Balancing:VLAN	Kindly remove VLAN as in a typical LIMS scenraio does not require load balancing at a level of VLAN .Rather load balancing is done using standard ways of Session/Flow based (Source IP, Destination IP, Source port, Dest Port addresses/Protocol).In the recent RFP's from various government on LIMS in India ;VLAN has never been criteria for load balancing .		See corrigendum-III
10	1.1	14	5(d)	Load balancing of all types of IP packets (IPv4 & 6) with different headers or encapsulations like MPLS, VLAN and etc. Load balancing of GTP headers should also support in case required in future by upgrading of Software/License/Hardware	Kindly remove MPLS,VLAN.The feature 'Load Balancing of IP packets with MPLS, VLAN and GTP headers' be removed from the specification as standard LIMS RFP from various Government agencies in India did not require load balancing using MPLS, VLAN and GTP headers .Rather load balancing is done using standard ways of Session/Flow based (Source IP, Destination IP, Source port, Dest Port addresses/Protocol)		See corrigendum-III
11	1.1	14	5 €	De-encapsulation or Striping of Labels/Headers for the protocols like MPLS, VLAN for entire input or output traffic and this feature should be part of the same box. De- encapsulation or Striping of Labels/Headers of GTP headers should also support in case required in future by upgrading ofSoftware/License/Hardware	.Kindly remove De-encapsulation or stripping feature for MPLS, GTP and VLAN as it is not required in any standard LIMS offering .Standard LIMS RFP from various Government agencies in India did not require load balancing using MPLS, VLAN and GTP headers .Rather load balancing is done using standard ways of Session/Flow based (Source IP, Destination IP, Source port, Dest Port addresses/Protocol)		See corrigendum-III
12	Note no. V of Chapter- 2	9	vii	Passive TAPs 10/100 Gigabit optical - 2 Nos. of quantity. Vendor may quote individual TAPs or group TAPs (e.g. 4 in One or more)	Please clarify total number of taps to be quoted .		See corrigendum-III
13	1.	15	6	VLAN support for <ul style="list-style-type: none"> • 802.1Q tag-based VLANs and trunking • Protocol-based VLAN • Management VLAN 	VLAN support for <ul style="list-style-type: none"> • 802.1Q tag-based VLANs and trunking • Protocol-based / dynamic VLAN • Management VLAN 	802.1x based dynamic vlan is common industry practice and should be considered. Requesting to modify clause for wider participation.	See corrigendum-III
14	1.4	16	1. viii.	Switch should comply to Operating Temperature range 0°C to 40 °C	Switch should comply to Operating Temperature range 0°C to 35 °C	Considering that the devices will be running in a much lower temperature under a controlled environment, please relax this clause for wider participation.	See corrigendum-III
15		16	2. ii.	IPv6 RIB/FIB: 2M/500K	IPv6 RIB/FIB: 2M/433K	Requesting to relax the clause for qualification of wider products.	See corrigendum-III
16		16	2. vi.	Firewall Filters: >4K	Firewall/ACL filters: >4K	Firewall term is not generally used for packet filtering use cases with router. Requesting to use Access control list (ACL) to avoid ambiguity.	See corrigendum-III
17		16	3. i.	Device should support Minimum 256K mac address	Device should support Minimum 224K mac address	Requesting to relax the clause for qualification of wider products.	See corrigendum-III

18		16	3. vii.	Device should support L2TP	Device should support L2TP/VXLAN+EVPN	VXLAN+EVPN are latest generation of protocols now becoming more common for layer-2 service on top of L3 network. Please allow VXLAN+EVPN as an option for wider participation. Also MPLS based layer-2 services (L2VPN, VPLS) are already asked in other clause.	See corrigendum-III
19		16	3. xiii.	Specifications for ISP Monitoring solution for RAILTEL ISP Gateways	Please remove the clause	Kindly remove this ambiguous clause or please clarify the clause requirement	See corrigendum-III
20		17	4. xiii.	Device should support CFM & LFM	Device should support CFM / LFM	requesting to remove LFM or make it optional for wider participation.	See corrigendum-III
21	1.2	14 & 15	7	Network Interface	Please clarify if we require 1G or 10 G NIC Card.		It is already mentioned
22	1.2 & 1.4	12 & 13	1.2 & 1.4.3	Clause 1.2 says the locations are New Delhi, Mumbai, Secunderabad, Chennai and Ernakulam. Clause 1.4.3 says the locations are Chennai, Delhi, Mumbai, Howrah, Ernakulam	1 location is different in these 2 clause Secunderabad or Howrah	Pls confirm the 5 locations	See corrigendum-III
23	1.4	12	1.4.1	ii) 220 volt single phase un-regulated power supply and +- 48 V DC	Railtel will provide power supply till the rack or DB	Pls confirm whether Railtel will provide power supply till the rack or till electric DB. If till electric DB then what will be the distance from DB to Rack and Power cable Spec – FRLS / NON FRLS thickness (in sq mm)	Railtel will provide power supply till the DB
24	1.2	12		OVERVIEW OF THE SCOPE OF WORK		1. Do we need do server clustering (HA, if yes required respective Redhat license and Subscription for same) 2. Do we need to support OS level support on site . 3. How will do patching of OS. 4. Do you require AV for Linux for OS level Security. 5. Nothing mentioned about virtualization, so we assume that their is no requirement for virtualization.	See corrigendum-III
25	1.2	14	2	Memory: 512 GB, DDR4-2933 (32x16 GB) , expandable to 1TB		512 GB, DDR4-2933 (32x16 GB) System should have 48 DIMMs and server supports a total of 12 TB of system memory	See corrigendum-III
26	1.2	14	6	Graphics: Integrated SVGA graphics interface		Integrated graphics interface	See corrigendum-III
27	1.2	14	9	I/O Ports: Minimum 4xUSB2.0, Keyboard, Optical Mouse		Minimum 1xUSB2.0, One VGA video port. 1x USB 3.1, Keyboard, Optical Mouse	See corrigendum-III
28	1.2	14	13	Supported OS: Red Hat® Linux® Enterprise v7 (Latest Version) (64 bit)Advanced Platform,		Red Hat® Linux® Enterprise v8 (Latest Version) (64 bit)Advanced Platform or higher	See corrigendum-III
29	1.2	14	14	OS to be supplied: Red Hat Enterprise V7 (Latest version) (64 bits) Linux Server Standard (up to 1 guest) 4 Sockets		Red Hat Enterprise V8 (Latest version) (64 bits) Linux Server Standard (up to 1 guest) 4 Sockets	See corrigendum-III
30	1.1	13				Specifications seems to be of Switch and not of Load Balancer. Pls confirm the exact requirement.	Specification is clear

31	1.1	13	1: No. Of Ports:	24 x 40/100 Gbps QSFP28 Ethernet ports with support of 40G QSFP & 100G QSFP and QSFP port should also be capable to support breakout to provide minimum 24x10G	As per CDOT standard specifications for LIM Application, they require minimum 32 x 40/100G Ports whereas you have mentioned only 24 x 40/100G Ports. Please reconfirm.		It is minimum requirement, however bidder is free to provide higher nos. of ports.
32	1.1	14	5: IP Packet Load Balancing:	<p>d. Load balancing of all types of IP packets (IPv4 & 6) with different headers or encapsulations like MPLS, VLAN and etc. Load balancing of GTP headers should also support in case required in future by upgrading of Software/License/Hardware.</p> <p>e. De-encapsulation or Striping of Labels/Headers for the protocols like MPLS, VLAN for entire input or output traffic and this feature should be part of the same box. De-encapsulation or Striping of Labels/Headers of GTP headers should also support in case required in future by upgrading of Software/License/ Hardware.</p>	We understand that this is part of standard specifications of CDOT but still we will require a confirmation whether stripping feature for MPLS/VLAN labels/headers is required by RailTel or Not. We also need to confirmation from whether MPLS and VLAN headers are available in their traffic		As per RFP
33	1.1	14	8: Supported and Equipped SFP's.	<p>12 x 100 Gb QSFP28-LR4 Ports and 12 x 100 Gb QSFP28-SR4 with 5m MPO Cable.</p> <p>3x 40G(4x10G)-LR4 (10KM support) with 5M MPO-4xLC breakout cable (5m), 3x40G(4x10G)-SR4 (100Mtr support) with MM MPO-4xLC breakout cable (5m)</p>	As per above mentioned details, 5 meter MPO Cable has been asked whereas in Item # 1.6, MPO Cables length is mentioned as 20m. Please confirm whether you need 5m MPO Cables or 20m MPO Cables		Both the requirements are separate.
34	1.2	14	1	Intel Xeon-Platinum processors-4 Nos Intel Xeon-Platinum 8260 (2.4GHZ\24-core\48 Theard,36MB cache,Turbo Ht,165W) or higher in terms of all parameter	<p>1- Intel Ice Lake processors which are of latest generation are already available since almost an year. These are latest generation processor with multiple performance benefits and other latest features.</p> <p>Kindly confirm if the dual socket server with the latest Intel 3rd Generation Processors can be considered.</p> <p>2- If 2nd generation processor needs to be considered, then requesting to rectify the cache value as per Intel datasheet.</p> <p>Intel 8260 Processor has 35.75 MB cache. Please correct the value as per Intel datasheet.</p>		See corrigendum-III
35	1.2	14	5	DVD ROM	Please confirm if the drives can be external. Kindly allow external drive for DVD-ROM		DVD ROM can be external
36	1.2	14	6	Integrated SVGA graphics interface	Please modify it as "Integrated SVGA/VGA graphics interface"		See corrigendum-III

37	1.2	14	7	High performance, PCI Express Gen 3.0 compliant, (a) 2xGigabit Ethernet NIC (10/100/1000 Mbps) (b)1x100 Gigabit (Mellanox Connect-X5 100 GbE with Mellanox SFP QSFP28) server Ethernet NIC with VLAN Tagging, IPV4 & IPV6 and teaming for failover and load balancing	(a) Please confirm port type required RJ45 or SFP+. (b) Please modify Mellanox SFP QSFP28/QSFP		a. Port type RJ45 b. SFP is used as generic term. No change in RFP specification.
38	1.2	15	8	8x PCIe Gen 3.0 (x16) I/O expansion slots (at least 4 Nos. PCIe x8 or above and at least 4 Nos. of PCIe x16 full length, Full Height)	Please modify it as " Minimum 6 x PCIe Gen 3.0 I/O expansion X8"		See corrigendum-III
39	1.2	15	9	Minimum 4xUSB2.0, Keyboard, Optical Mouse			See corrigendum-III
40	1.2	15	10	Hot Plug AC 230V/50Hz, Redundant Power supply	Please modify the clause as below: "Hot Plug AC 1600W/ 230V/50Hz, Redundant power supply"		As per RFP
41	1.2	15	13	Red Hat® Linux® Enterprise v7 (Latest Version) (64 bit) Advanced Platform	RHEL 7.9 onwards. RHEL 9.0 is the latest		See corrigendum-III
42	1.4	16	2	i. IPv4 RIB/FIB- 10M /1M	We understand that this is remote site connectivity for remote Data Center with a L2/L3 Switch. Kindly reduce IPv4 RIB/FIB to 5M/500K		As per RFP
43				ii. IPv6 RIB/FIB- 2M/500K	We understand that this is remote site connectivity for remote Data Center with a L2/L3 Switch. Kindly reduce IPv6 RIB/FIB to 5M/500K		See corrigendum-III
44				iii. MPLS Labels - 32K	We understand that this is remote site connectivity for remote Data Center with a L2/L3 Switch. Kindly reduce MPLS label to 1500		As per RFP
45	1.4	17	4	xiii. Device should support CFM & LFM	Kindly delete this or include IPSLA or CFM & LFM or UDLD		See corrigendum-III
46	1.1	14	5(a)	IP Packet Load Balancing:VLAN	Kindly remove VLAN as in a typical LIMS scenraio does not require load balancing at a level of VLAN .Rather load balancing is done using standard ways of Session/Flow based (Source IP, Destination IP, Source port, Dest Port addresses/Protocol).In the recent RFP's from various government on LIMS in India ;VLAN has never been criteria for load balancing .		See corrigendum-III
47	1.1	14	5(d)	Load balancing of all types of IP packets (IPv4 & 6) with different headers or encapsulations like MPLS, VLAN and etc. Load balancing of GTP headers should also support in case required in future by upgrading of Software/License/Hardware	Kindly remove MPLS,VLAN.The feature 'Load Balancing of IP packets with MPLS, VLAN and GTP headers' be removed from the specification as standard LIMS RFP from various Government agencies in India did not require load balancing using MPLS, VLAN and GTP headers .Rather load balancing is done using standard ways of Session/Flow based (Source IP, Destination IP, Source port, Dest Port addresses/Protocol)		See corrigendum-III

48	1.1	14	5(e)	De-encapsulation or Striping of Labels/Headers for the protocols like MPLS, VLAN for entire input or output traffic and this feature should be part of the same box. De- encapsulation or Striping of Labels/Headers of GTP headers should also support in case required in future by upgrading of Software/License/Hardware	Kindly remove De-encapsulation or stripping feature for MPLS, GTP and VLAN as it is not required in any standard LIMS offering . Standard LIMS RFP from various Government agencies in India did not require load balancing using MPLS, VLAN and GTP headers . Rather load balancing is done using standard ways of Session/Flow based (Source IP, Destination IP, Source port, Dest Port addresses/Protocol)		See corrigendum-III
49	1.3	15	6	VLAN support for Protocol-based VLAN	Protocol based VLAN specific to particular OEM. Kindly help to delete it.		See corrigendum-III
50	1.4	16	3(xiii)	Specifications for ISP Monitoring solution for RAILTEL ISP Gateways	Need clarity on the clause. Does it mean SNMP on the device.		See corrigendum-III
51	1.2	12		The scope of work would be Supply along with Installation, Testing, Commissioning & Integration of all the networking equipments i.e. Linux servers, TAPS, switches etc for Lawful interception monitoring system at five locations viz New Delhi, Mumbai, Secunderabad, Chennai and Ernakulam.	one of Site location is secundrabad but as per clause 1.4.3 secundrabas site replaced by Howrah. please clarify		See corrigendum-III
52	1.4	12	1.4.1	i) Air-conditioned space for housing equipments. ii) 220 volt single phase un-regulated power supply and +- 48 V DC	Railtel responsibility 220 volt unregulated power supply, but all the SOR equipmnet require Unintrupted Power supply.		unregulated means it is AC power supply
53	1.2	14 & 15	14	OS to be supplied Red Hat Enterprise V7 (Latest version) (64 bits) Linux Server Standard (up to 1 guest) 4 Sockets	Specifications of Servers (Item no. 2 of SOR-A): OS to be Supplied Red Hat Enterprise V7 (Latest version) (64 bits) Linux Server Standard (up to 1 guest) 4 Sockets - in the contest please confirm that all the servers are deployed in standalone mode.		All servers to be deployed in standalone mode . Also See corrigendum-III
54	1.4	16	2 / i.	IPv4 RIB/FIB	10M /1M	We understand that this is remote site connectivity for remote Data Center with a L2/L3 Switch. Kindly reduce IPv4 RIB/FIB to 5M/500K	As per RFP
55	1.4	16	2 / ii.	IPv6 RIB/FIB	2M/500K	We understand that this is remote site connectivity for remote Data Center with a L2/L3 Switch. Kindly reduce IPv6 RIB/FIB to 2M/500K	As per RFP
56	1.4	16	2 / iii.	MPLS Labels	32K	We understand that this is remote site connectivity for remote Data Center with a L2/L3 Switch. Kindly reduce MPLS label to 1500	As per RFP
57	1.4	17	4 / xiii.	Device should support CFM & LFM	Device should support IPSLA	Kindly delete this or include IPSLA or CFM & LFM or UDLD	See corrigendum-III
58	1.4	16	1 / i.	Switch should have at least 24 number of 10 Gbps interfaces support and 12x100 Gbps QSFP interfaces with on Day 1. 10 Gbps interfaces through breakout cable shall also be acceptable with LR optics		Kindly suggest number of optics for 100G and 10G to be proposed. Please also suggest optics type with distance for multimode or single mode type.	As per RFP
59	1.3	15	6	VLAN support for • 802.1Q tag-based VLANs and trunking • Protocol-based VLAN • Management VLAN	VLAN support for • 802.1Q tag-based VLANs and trunking • Protocol-based / dynamic VLAN • Management VLAN	802.1x based dynamic vlan is common industry practice and should be considered. Requesting to modify clause for wider participation.	See corrigendum-III

60	1.4	16	1. viii.	Switch should comply to Operating Temperature range 0°C to 40 °C	Switch should comply to Operating Temperature range 0°C to 35 °C	Considering that the devices will be running in a much lower temperature under a controlled environment, please relax this clause for wider participation.	See corrigendum-III
61		16	2. ii.	IPv6 RIB/FIB: 2M/500K	IPv6 RIB/FIB: 2M/433K	Requesting to relax the clause for qualification of wider products.	See corrigendum-III
62		16	2. vi.	Firewall Filters: >4K	Firewall/ACL filters: >4K	Firewall term is not generally used for packet filtering use cases with router. Requesting to use Access control list (ACL) to avoid ambiguity.	See corrigendum-III
63		16	3. i.	Device should support Minimum 256K mac address	Device should support Minimum 224K mac address	Requesting to relax the clause for qualification of wider products.	See corrigendum-III
64		16	3. vii.	Device should support L2TP	Device should support L2TP/VXLAN+EVPN	VXLAN+EVPN are latest generation of protocols now becoming more common for layer-2 service on top of L3 network. Please allow VXLAN+EVPN as an option for wider participation. Also MPLS based layer-2 services (L2VPN, VPLS) are already asked in other clause.	See corrigendum-III
65		16	3. xiii.	Specifications for ISP Monitoring solution for RAILTEL ISP Gateways	Please remove the clause	Kindly remove this ambiguous clause or please clarify the clause requirement	See corrigendum-III
66		17	4. xiii.	Device should support CFM & LFM	Device should support CFM / LFM	requesting to remove LFM or make it optional for wider participation.	See corrigendum-III
67	1.3	15	6	VLAN Support for : . Protocol - Based VLAN	Request you to remove this point or make it optional	As this point is not common for all the OEMs. As Juniper OEM doesn't support this protocol. This change will help Juniper to participate.	See corrigendum-III
68	1.4	16	3 (xiii)	Specifications for ISP Monitoring solution for RAILTEL ISP Gateways	We are not understood about this clause . Kindly give us more information on this point.		See corrigendum-III
69	1.3	15	6	VLAN support for *802.1Q tag-based VLANs and trunking *Protocol-based VLAN *Management VLAN	Request you to please make Protocol- based VLAN clause as optional		See corrigendum-III
70	1.4	16	3(xiii)	Specifications for ISP Monitoring solution for RAILTEL ISP Gateways	The clause is not clear. Kindly provide clarification on the same		See corrigendum-III

Commercial terms & conditions:-

SN	Clause No. & Chapter	Page No.	Sub Clause no./Point no.	Content of the clause requires clarification	Points of clarification required	Remarks	RailTel's Resonse
1	4.A.5, Chapter-4A	21	4.A.5.1	<p>75% payment of the PO value would be made on receipt of material by the consignee (at site/the stores, to be decided by CNOC/respective regional ED/RGMs) duly inspected and on submission of the following documents subject to any deductions or recovery which RailTel may be entitled to make under the contract:</p> <p>(i) Valid Tax Invoice (ii) Delivery Challan/ E-way bill (iii) Packing list. (iv) Factory Test Report. (v) Purchaser's Inspection certificate (vi) Consignee receipt (vii) Warranty certificate of OEM (viii) Insurance certificate (ix) A certificate duly signed by the firm certifying that equipment/ materials being supplied are new and conform to technical specification.</p> <p>4.A.5.2 15% payment of the PO value shall be made by RailTel on Installation, Testing, Commissioning & Integration at site and Site Acceptance Report issued by CNOC & Region. Further 5% payment of the PO value shall be made by RailTel on issue of Provisional Acceptance Certificate (PAC)/Part PAC by CNOC. Last 5% payment of the PO value shall be made by RailTel on issue of Final Acceptance Certificate (FAC) by CNOC.</p>	<p>We request you to kindly amend this clause as:</p> <p>85% value of PO Value would be made on receipt of material by the consignee duly inspected and on submission of the following documents subject to any deductions or recovery which RailTel may be entitled to make under the contract:</p> <p>(i) Valid Tax Invoice (ii) Delivery Challan/ E-way bill (iii) Packing list. (iv) Factory Test Report. (v) Purchaser's Inspection certificate (vi) Consignee receipt (vii) Warranty certificate of OEM (viii) Insurance certificate (ix) A certificate duly signed by the firm certifying that equipment/ materials being supplied are new and conform to technical specification.</p> <p>10% payment of the value of delivered equipment(s) will be released after successful commissioning and acceptance.</p> <p>Last 5% payment of the PO value shall be made by RailTel on issue of Final Acceptance Certificate (FAC) by CNOC.</p>		As per RFP
2	4.A.4, Chapter-4A	21		<p>The materials as per SOR-A are required to be delivered, installed, tested, commissioned & Integrated within 120 days from the issue of LOA/Purchase Order. The bidder is required to submit the PERT chart showing the various activities which are required for supply, installation, testing, commissioning and integration of the equipment.</p>	<p>We request you to kindly amend this clause as:</p> <p>Contractor shall complete the delivery, installation, testing and commissioning of all the equipment(s) at all sites within 280 days from the date of issuance of Contract.</p> <p>Considering Global Semiconductor issue ,all OEM are having delivery timeline of 36 to 40 Weeks.Request to increase the timeline to 40 Weeks</p>		See corrigendum-III
	7.4.1, Chapter-7	78-79	7.4.1.1	<p>Delivery Period: The received defective part will be got repaired by the contractor within 30 days from the date of receiving and will be installed/handed over to RailTel authorized representative at NOC/site. The contractor will also give probable reason for repeated failure of cards/ modules.</p>	<p>we request you to kindly amend this clause as:The received defective part will be got repaired by the contractor within 60 days from the date of receiving and will be installed/handed over to RailTel authorized representative at NOC/site. The contractor will also give probable reason for repeated failure of cards/ modules</p>		See corrigendum-III

3	4.A.4, Chapter-4A	21		The materials as per SOR-A are required to be delivered, installed, tested, commissioned & Integrated within 120 days from the issue of LOA/Purchase Order. The bidder is required to submit the PERT chart showing the various activities which are required for supply, installation, testing, commissioning and integration of the equipment. The materials shall be delivered to the site as given in clause 1.4.3 of chapter-3. Consignee address and details will be provided to the successful bidder.	Due to worldwide issue of componets and its lead time;hardware delivery timelies of product are impacted.Accrodingly we hereby request you to change the overall period from existing 120 days to 180 days.This will ensure that siuch delays are planned before and LD's are not accounted for .Otherwise contingencies are kept which lead to increased project cost		See corrigendum-III
4	4.A.3, Chapter-4A	20	4.A.3.1	Bidder/OEM shall provide maintenance support after successful completion of the warranty obligations for a minimum period of 5 years for item no. 1, 2, 3 & 4 of SOR-A	Bidder/OEM shall provide maintenance support after successful completion of the warranty obligations for a minimum period of 3 years for item no. 1, 2, 3 & 4 of SOR-A	8 yrs is a very long period for a product life cycle. Products are generally refreshed in 5 to 6 yrs due to technology obsolescence. Therefore requesting to reduce the upfront maintenance support to 3 Yrs.	As per RFP
5	4.A.4, Chapter-4A	21	4.A.4	The materials as per SOR-A are required to be delivered, installed, tested, commissioned & Integrated within 120 days from the issue of LOA/Purchase Order.	The materials as per SOR-A are required to be delivered, installed, tested, commissioned & Integrated within 12 Months from the issue of LOA/Purchase Order.	Considering the chip shortage across industry for various hardware components, requesting to change the period to 12 Months.	See corrigendum-III
6	4.A.5, Chapter-4 A	21	4.A.5.1	75% payment of the PO value would be made on receipt of material by the consignee (at site/the stores, to be decided by CNOC/respective regional ED/RGMs) duly inspected and on submission of the following documents subject to any deductions or recovery which RailTel may be entitled to make under the contract:	80% payment of the PO value would be made on receipt of material by the consignee (at site/the stores, to be decided by CNOC/respective regional ED/RGMs) duly inspected and on submission of the following documents subject to any deductions or recovery which RailTel may be entitled to make under the contract:		As per RFP
7	4.A.22, Chapter-4 A	40	4.A.22.1	All the Bidders/OEM are required to deposit Tender Cost and EMD amount as mentioned in NIT and BDS through e-Nivida Portal as "Tender Cost" & "Earnest Money". Tender cost and EMD in no other form shall be accepted. Offers without applicable EMD amount and tender cost shall be summarily rejected.	Request the department to allow the submisison of EMD in the form of Bank Guarantee.		As per RFP
8	4.A.12.2, Chapter-4A	25	2	Financial Capability	The bidder should have received a minimum cumulative contract of Rs. 3.5 Crs from the operations in the last three financial years plus current year upto the date of opening of tender		As per RFP
9	4.A.12.2, Chapter-4A	25	3	Technical capability	Single order costing not less than Rs. 3.5 Crs related to IT infrastructure projects.		As per RFP
10	4.A.4, Chapter-4A	21		Delivery, installation, testing, commissioning & Integration within 120 days from the issue of LOA/Purchase Order.	Due to ongoing worldwide shortage of chips, delivery of Network switches are anormous delay by all the OEMs. Current delivery timelines are ranging from 9 to 15 months which varies from OEM to OEM.	Requested to please change the delivery timelines from 120 days to at least 300 days.	See corrigendum-III

11	4.A.5, Chapter-4A	21	4.A.5.1	75% payment of the PO value would be made on receipt of material by the consignee 15% payment of the PO value shall be made on Installation, Testing, Commissioning & Integration at site and Site Acceptance Report issued by CNOC & Region. Further 5% payment of the PO value shall be made by RailTel on issue of Provisional Acceptance Certificate (PAC)/Part PAC by CNOC. Last 5% payment of the PO value shall be made by RailTel on issue of Final Acceptance Certificate (FAC) by CNOC.	Due to ongoing worldwide shortage of chips, delivery of network switches are delay but all other equipments can be delivered and installed within 120 days	Requested you to pls change it to "75% payment of the delivered item would be made on receipt of material by the consignee 15% payment of the delivered item shall be made on Installation, Testing, Commissioning & Integration at site and Site Acceptance Report issued by CNOC & Region. Further 5% payment of the delivered item shall be made by RailTel on issue of Provisional Acceptance Certificate (PAC)/Part PAC by CNOC. Last 5% payment of the delivered item shall be made by RailTel on issue of Final Acceptance Certificate (FAC) by CNOC."	As per RFP
12	4.A.22, Chapter-4 A	40	4.A.22.1	All the Bidders/OEM are required to deposit Tender Cost and EMD amount as mentioned in NIT and BDS through e-Nivida Portal as "Tender Cost" & "Earnest Money". Tender cost and EMD in no other form shall be accepted. Offers without applicable EMD amount and tender cost shall be summarily rejected.		Requested you to pls allow to submit the EMD in the form of Bank Guarantee.	As per RFP
13	4.A.3 & 4.A.6, Chapter-4A	20 22	Clause: 4.A.3.3 Clause: 4.A.6.1	Value of PBG will be 10% of the total value of issued LOA for five years or will be kept as per Government of India guidelines applicable at the time of issue of LOA for AMC. The tenderer bidder has to furnish security deposit in the form of Performance Bank guarantee @ 3% of issued PO/ LOA value, the same should be submitted within 30 days of issue of LOA/PO, failing which a penal interest of 15% per annum shall be charged for the delay period i.e. beyond 30 (thirty) days from the date of issue of LOA/PO	Since bidder will provide BG @3% after LOI, We request you to please accept BG against AMC @3% instead of 10% against for Long Terms maintenance.		As per RFP
14	4.A.4	21		The materials as per SOR-A are required to be delivered, installed, tested, commissioned & Integrated within 120 days from the issue of LOA/Purchase Order. The bidder is required to submit the PERT chart showing the various activities which are required for supply, installation, testing, commissioning and integration of the equipment. The materials shall be delivered to the site as given in clause 1.4.3 of chapter-3. Consignee address and details will be provided to the successful bidder.	Due to worldwide issue of componets and its lead time; hardware delivery timelies of product are impacted. Accrodingly we hereby request you to change the overall period from existing 120 days to 180 days. This will ensure that siuch delays are planned before and LD's are not accounted for . Otherwise contingencies are kept which lead to increased project cost		See corrigendum-III
15	4.A.41, Chapter-4A	45	4.A.41.1	Preference to Make in India:	As per the technical specifications and project requirement, all the products available in market does not fall under category I and II. Hence we request you to kindly remove this clause to provide the fully complained solution		As per RFP

16	4.A.41	45	4.A.41.1	Preference to Make in India:	Most of the Equipments asked in this tender are high end IT equipment and leading OEMs for these equipment do not manufacture Made in India products. So, request you to allow Non-Make In India Products to be bided.	Most of the Equipments asked in this tender are high end IT equipment and leading OEMs for these equipment do not manufacture Made in India products to meet Class-1 or Class-2 supplier requirement. So, request you to allow Non-Make In India Products to be bided.	As per RFP
17	4.A.12.2, Chapter-4A	25	1	Legal Entity: The bidder should be a Company registered in India under the Companies Act (India) with their registered office in India for the last three years.	The bidder should be a Company registered in India under the Companies Act (India) with their registered office in India for the last three Financial years. FY 19-20, FY 20-21, FY 21-22	Please ask for registered office in India for the last three Financial years. FY 19-20, FY 20-21, FY 21-22 and Three Financial year balance sheet required.	See corrigendum-III
18	4.A.12.2, Chapter-4A	25	1	Legal Entity: The bidder should be a Company registered in India under the Companies Act (India) with their registered office in India for the last three years.	in the RFP, Startup and MSME organizations have been given relaxation on the eligibility criteria. We also request you to consider relaxation for this clause as well and allow Startup registered under DPIIT are allowed to participate, if they have completed 3 financial years. We have completed three Financial years (FY19-20, FY20-21, FY21-22) and current FY 22-23 is our fourth financial year from incorporation. We also wish to highlight that we are registered MSME Vendor (UDYAM-UP-29-0014835) and also registered Startup under Department for Promotion of Industry and Internal Trade, Ministry of Commerce & Industry, Government of India, Certificate No.: DIPP49350. We are also Business Partner of RailTel Corporation through letter Number: RailTel/EOI/EB/2020-21/IT-ICT Partner/479A dated 19th January, 2022. Request you kindly allow us to participate and amend the clause as " The Bidder should have registered office in India for a minimum period of 3 Financial years as on scheduled date of bid opening. Certificate of incorporation will have to be submitted."		See corrigendum-III
19	4.A.4	21		The materials as per SOR-A are required to be delivered, installed, tested, commissioned & Integrated within 120 days from the issue of LOA/Purchase Order.	The materials as per SOR-A are required to be delivered, installed, tested, commissioned & Integrated within 12 Months from the issue of LOA/Purchase Order.	Considering the current Covid, Logistic's & chip shortage across industry for various hardware components, facing delay in delivery of hardware equipments so requesting to change the period to 12 Months.	See corrigendum-III
20	4.A.3	20	4.A.3.1	Bidder/OEM shall provide maintenance support after successful completion of the warranty obligations for a minimum period of 5 years for item no. 1, 2, 3 & 4 of SOR-A	Bidder/OEM shall provide maintenance support after successful completion of the warranty obligations for a minimum period of 3 years for item no. 1, 2, 3 & 4 of SOR-A	8 yrs is a very long period for a product life cycle. Products are generally refreshed in 5 to 6 yrs due to technology obsolescence. Therefore requesting to reduce the upfront maintenance support to 3 Yrs.	As per RFP

21	4.A.41	45	4.A.41.1	Preference to Make in India:	i. Only Class-I local suppliers (meeting minimum 50% local content) & Class-II local suppliers (meeting minimum 20% local content) are eligible to participate in this tender.	Most of the Equipment's asked in this tender are high end IT equipment and leading OEMs for these equipment do not manufacture Made in India products to meet Class-1 or Class-2 supplier requirement. We would like to request you to please allow Non-Make in India Products.	As per RFP
22	4.A.12.2	25	1	Legal Entity: The bidder should be a Company registered in India under the Companies Act (India) with their registered office in India for the last three years.	The bidder should be a Company registered in India under the Companies Act (India) with their registered office in India for the last three Financial years. FY 19-20, FY 20-21, FY 21-22	Please ask for registered office in India for the last three Financial years. FY 19-20, FY 20-21, FY 21-22 and Three Financial year balance sheet required.	See corrigendum-III
23	4.A.41	45	4.A.41.1	Preference to Make in India:	i. Only Class-I local suppliers (meeting minimum 50% local content) & Class-II local suppliers (meeting minimum 20% local content) are eligible to participate in this tender.	Leading OEMs do not manufacture Make in India products to fall under Class-1 or Class-2 supplier requirement. We would like to request you for an exemption of Make in India Products.	As per RFP
24	4.A.12.2	25	1	Legal Entity: The bidder should be a Company registered in India under the Companies Act (India) with their registered office in India for the last three years.	The bidder should be a Company registered in India under the Companies Act (India) with their registered office in India for the last three Financial years. FY 19-20, FY 20-21, FY 21-22	Request you to please consider last three balance sheet instead of last three year bidder's presence.	See corrigendum-III